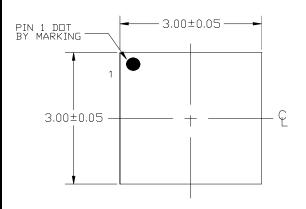


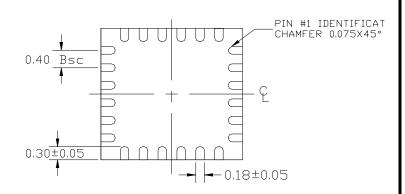
## TITLE

24 LEAD QFN 3x3mm PACKAGE (Flip Chip) OUTLINE & RECOMMENDED LAND PATTERN

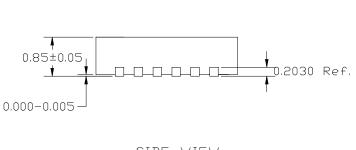
DRAWING #	FQFN33-24LD-PL-1	UNIT	MM
Lead Frame	NiPdAu	Lead Finish	NiPdAu



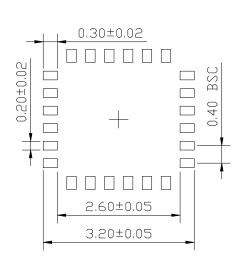
TOP VIEW NDTE: 1, 2, 3



BOTTOM VIEW NOTE: 1, 2, 3



SIDE VIEW NDTE: 1, 2, 3



## RECOMMENDED LAND PATTERN

## NOTE:

- 1. MAX PACKAGE WARPAGE IS 0.05 MM 2. MAX ALLOWABLE BURR IS 0.076MM IN ALL DIRECTIONS
- 3. PIN #1 IS ON TOP WILL BE LASER MARKED

Rev	ECN	Originator	Change	Reason
А	111512HC03	A. Kungo	New release	Replaces QFN33-24LD-PL-9